

ABSTRACT

An adhesive composition containing an epoxy resin (A), an epoxy resin curing agent (B), a polyurethane resin (C), and an inorganic filler (D), wherein the
5 polyurethane resin (C) has a $\tan \delta$ peak top temperature of 0°C or higher in dynamic mechanical analysis, and the proportion of the polyurethane resin (C) based on the total content of the epoxy resin (A) and the polyurethane resin (C) is from 2 to 50 mass%.

(No Suitable Figure)